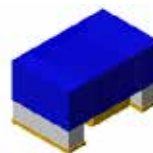


MATERIAL DECLARATION SHEET



Material Number	CW100505 Series			
Product Line	Wound Chip Inductor			
Compliance Date	6-1-2003			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	CERAMIC CORE	CERAMIC	0.55	Aluminum oxide (Al2O3)	1344-28-1	97.7%	67.169%	68.75
				Silicon dioxide (SiO2)	14808-60-7	2.3%	1.581%	
		Plating	0.15	Molybdenum	7439-98-7	33.0%	6.490%	6.49
				Manganese	7439-96-5	33.0%	6.490%	6.49
				Nickel (Ni)	7440-02-0	33.0%	4.327%	4.33
				Gold (Au)	7440-57-5	1.0%	1.442%	1.44
2	COPPER WIRE	Copper	0.028	Copper(Cu)	7440-50-8	99.95%	3.558%	3.56
				Misc. ,not to declare	\	0.05%	0.002%	
		Resin	0.002	Polyurethane	9009-54-5	100.0%	0.190%	0.19
3	EPOXY	EPOXY	0.07	Polyurethane	51852-81-4	25.0%	2.188%	8.75
				(2E)-3-{{{(1E)-3-{4-[2-(4-Hydroxyphenyl)-2-propanyl]phenoxy}-3-oxo -1-propen-1-yl]oxy}acrylic acid	55818-57-0	50.0%	4.375%	
				Isobornyl methacrylate	7534-94-3	17.0%	1.488%	
				4-Acryloylmorpholine	5117-12-4	5.0%	0.438%	
				2,2-Dimethoxy-2-phenylacetophenone	24650-42-8	3.0%	0.263%	
		Total weight	0.8					

This Document was updated on: 2024/11/6

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.